



Conditions for assembly from materials provided by the client

Minimum requirements:

SMD components:

- Should be delivered in labelled production packaging, such as reels (tapes), strips, trays. Labels should at minimum contain: full name of the component (preferably MPN), quantity and MSL level (where required).
- Components sensitive to moisture (MSL>1) should be packed in accordance with the IPC/JEDEC J-STD-033 standard.
- Components sensitive to electrostatic discharges should be labelled and packed in accordance with manufacturer's requirements.
- Components delivered in reels should include at minimum 50 mm of carrier tape (with no components) and 200 mm of cover tape, or alternatively at least 250 mm of both carrier tape and cover tape. The tape should not be cut into sections or fragments.
- Components with one of the dimensions (width or length) lower than 7 mm should be delivered only on tapes or strips; components with either dimension lower than 5 mm should be delivered only on tapes.

THD components:

- Should be delivered in labelled production packaging, such as reels or sections of tapes, strips, trays. The only exception is LED diodes that can be delivered loose.

Mechanical components:

- Should be delivered in manufacturer's packaging.

All components:

- Depending on the type, they should be delivered in uncut and unbroken strips or trays.
- They should be delivered with an appropriate surplus, as per the "Required Production Surplus" table. After prior consultation, it is acceptable to deliver the components without the required surplus, e.g. due to a high price of a component, limited availability, or for other important reasons – such information must be included on the list of components provided.
- Each shipment must include a list of components provided, in an electronic, editable format (the template of a correctly filled table can be found in this manual on page 4), containing at minimum the markings of the components (MPN) in accordance with the BOM list and the description on the packaging, MSL level (acc. IPC/JEDEC J-STD-033) and the amounts provided. **If the MSL level is not entered, the component is considered not sensitive to moisture.** In case of replacements, it is necessary to enter them in the appropriate column. The marking of the replaced original component must be provided. In case of own part numbers, it is necessary to enter them in the appropriate column.

NOTE:

- Minimum quantity for RLC components is **50 pcs**.
- Any discrepancies from the above-mentioned requirements may lead to **additional fees**.
- The production surplus is required for the completion of the assembly service – **failing to deliver it may result in production shortages**.

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Conditions for assembly from materials provided by the client – „Requirements for electronics assembly from components provided” table

Requirements for electronics assembly from entrusted parts							
Type of component	SMD			THD			Other components
Acceptable packaging	Tape	Strip	Tray	Roll	Strip	Tray	Manufacturer's packaging
Minimum component dimensions	No requirements	5 mm x 5 mm	7 mm x 7 mm	No requirements			No requirements
Components with MSL > 1	Packed in accordance with IPC/JEDEC J-STD-033 standard						
Components sensitive to ESD	Packed in accordance with manufacturer's requirements						
Labelling	Label containing MPN (and/or full name), quantity and other markings (if necessary)						
Additional requirements	Min. 50 mm of carrier tape + 200 mm of cover tape (both ends)	Tube as a whole – uncut	Tray with components – unbroken	No additional requirements			No additional requirements

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Conditions for assembly from materials provided by the client – „Required Production Surplus” table

Required production surplus

Type of component		SMD							THD		Other		
Number of pins/component type		2		3–5	>6	QFP, QFN, BGA			Other	2	>2	Mechanical components	Other
		size <0603	size ≥0603										
Type of packaging		any	any	any	any	tape	tube	tray	any	any	any	any	
Quantity (pcs.)	1–20	20*	10*	10	5	5	3	3	1	5	1	1%	1%
	21–100	20*	10*	5	3%	2%	5%	2%	5%	1	1	1%	1%
	101–1000	3%*	2.5%*	3%	2%	1%	1%	1%	1%	1%	1%	1%	1%
	>1000	2%*	1.5%*	2%	1,5%	1%	1%	1%	1%	1%	1%	1%	1%

* minimum quantity for delivered RLC components is 50 pcs.

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Conditions for assembly from materials provided by the client – an example of correctly filled-in list of components provided

P.PR1.F16_rev.04_16.04.2024
List of components provided

Scheduled delivery date 16.04.2024

Customer Name*	xyz
Project Name*	abc
Version/Review*	1
PCB Quantity*	10
Estimated value of provided components*	10.000 EUR

No	Product group	MPN*	Description*	Replacement*	MSL Level*	Customer parts number	Desygnator	Pcs./PCB*	Pcs./Order*	Pcs. dispensed*	Pcs. received	Difference	Remarks
1.	Fuses	0154003.DRT	Fuse: ceramic; 3A; 125VAC; 125VDC			01-12345	B1	1	122	300	300	0	F_0154003.DRT_125V_3A_ND_SMD_2410
2.	EMIs	EMIT0603U601	High Current Ferrite Bead: EMI SMD 0603			01-23346	L1-L16	16	1952	4000	4000	0	L_EMIT0603U601_1A_25%_SMD_0603_H0.8
3.	Diodes	ZSMD-15V	Zener diode: ZSMD-15V ; 0,5W; 15V; MINIMELF	BZV55C15 TZMC15-GS08		01-34347	D1	1	122	450	450	0	D_15V_SMD_MINIMELF
4.	Capacitor	CL10B104K88NNNC	Ceramic capacitor: SMD 0603 CL10B104K88NNNC	CL10B104J88NNNC		01-45348	C1-C38	38	380	8000	8000	0	C_100n_50V_10%_X7R_SM_D_0603_H0.8
5.	Resistors	RC0603FR-07100KL	Resistor SMD 0603	SMD0603-100K-1%		01-56349	R1-R5	5	610	4000	4000	0	R_100k_0.1W_1%_SMD_0603_H0.35
6.	Transistor	BC807- 40	Bipolar transistor: PNP; 50V; 500mA; SOT23 SMD	BC807-25		01-67350	T1	1	122	300	300	0	T_BC807- 40_PNP_NXP_SMD_SOT-23
7.	Ics	HEF4013BT	IC: D-type flip-flop; SOP14 NXP			01-78351	U1	1	122	300	300	0	U_HEF4013BT_CMOS_NXP_SMD_SOP14-N
8.	Diodes	HFA15TB60	Single diode: 600V; 15A		MSL1	01-89352	D1-D2	2	20	244	300	0	D_HFA15TB60_THT_TO220-2-v
9.	Connectors	T821-1-06-S1	Socket IDC: T821-1-06-S1; men; PIN-6; straight; THT; gold-plated; 2,54mm			02-00353	J1	1	122	230	230	0	J_T821-1-06-S1_IDC_AMPHENOL_THT_P-KG_T821-1-06-S1_R2.54-V
10.	PCB	MOT_V12	PCB: 4-layers; FR4; 1,6mm; ENIG; finish copper ext. 35um; silkscreen white; soldermask green; E-test; etc.			02-11354	PCB	1	122	122	122	0	PCB

Legend	
<field_name>*	Should be filled mandatory by the Customer
	Filled by the Customer
	Filled by Semicon
	Filled by the Customer/Semicon

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Conditions for assembly from materials provided by the client – an example of correctly and incorrectly described and delivered components

